

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANT: C. Huang CONF. NO.: 7288

U.S. SERIAL NO: 10/696,198 EXAMINER: H. Trinh

FILED: October 28, 2003 GROUP: 2814

FOR: MULTI-CHIP PACKAGE DEVICE WITH HEAT SINK AND  
FABRICATION METHOD THEREOF

please do not enter  
/ (Vikki) Hoa B.  
Trinh/

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir/Madam:

**AMENDMENT**

Applicant is in receipt of the Office Action dated May 30, 2007 of the above-referenced application. Please amend the application as follows:

**Amendments to the claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 4 of this paper.